

Amendments to the Specification:

Please delete the paragraph at page 6, lines 13-18, and substitute therefor the following new paragraph:

The adhesive film according to any one of <1> to <5>, wherein as-the (A) polyimide resin contains one or more kinds of polyimide resin, one of the polyimide resins is obtained by reacting a diamine and an acid dianhydride satisfying the condition where a difference between a heat generation initiating temperature and a heat generation peak temperature by means of DSC is 10°C or smaller, and the polyimide obtained by reacting the diamine and the acid dianhydride, ~~a polyimide resin obtained by reacting an acid dianhydride satisfying the condition where a difference between a heat generation initiating temperature and a heat generation peak temperature is 10°C or smaller, and diamine is contained at 50% by weight or more of a total polyimide resin.~~

Please delete the paragraph bridging pages 57 and 58 of Applicants' specification (that is, from page 57, line 19, to page 58, line 3), and substitute therefor the following new paragraph:

The urethane acrylate-based oligomer can be obtained, for example, by reacting a polyol compound of polyester type or polyether type with a polyvalent isocyanate compound such as 2,4-tolylenediisocyanate, 2,6-tolylenediisocyanate, 1,3-xylylenediisocyanate, 1,4-xylylenediisocyanate, ~~diphenylmethane, 4,4-diisocyanate~~ 4,4-diphenylmethane diisocyanate and the like to obtain a terminal isocyanate urethane prepolymer, which is reacted with acrylate or methacrylate having a hydroxyl group, such as 2-hydroxyethyl

acrylate, 2-hydroxyethyl methacrylate, 2-hydroxypropyl acrylate, 2-hydroxypropyl methacrylate, polyethylene glycol acrylate, polyethylene glycol methacrylate and the like.